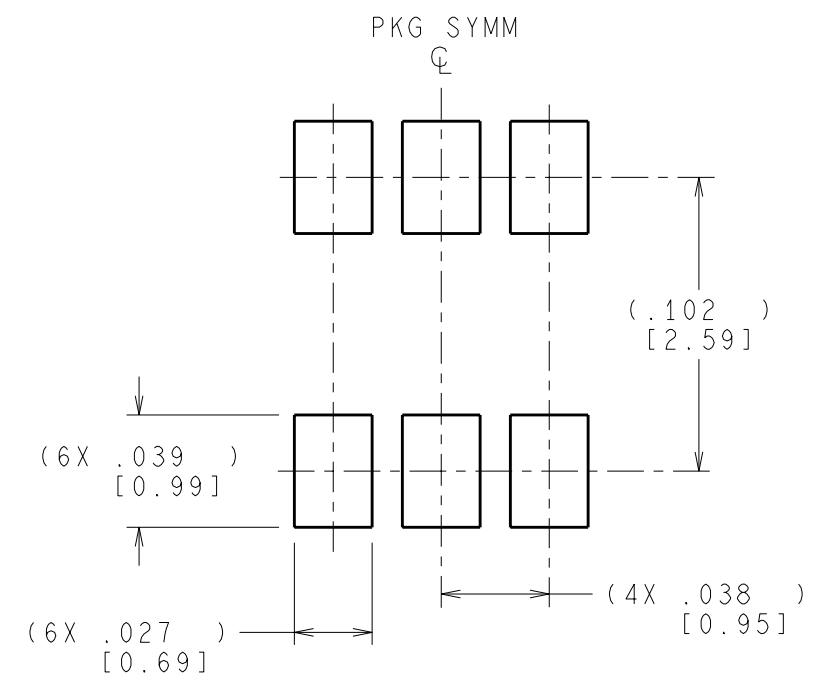
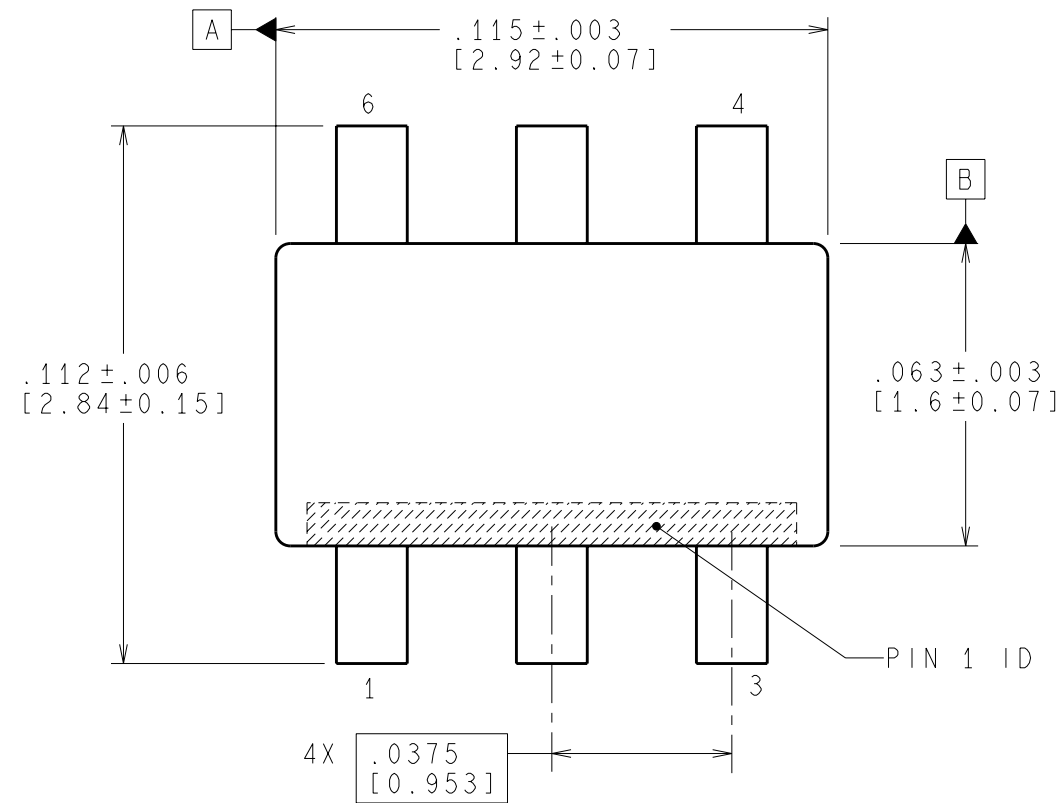
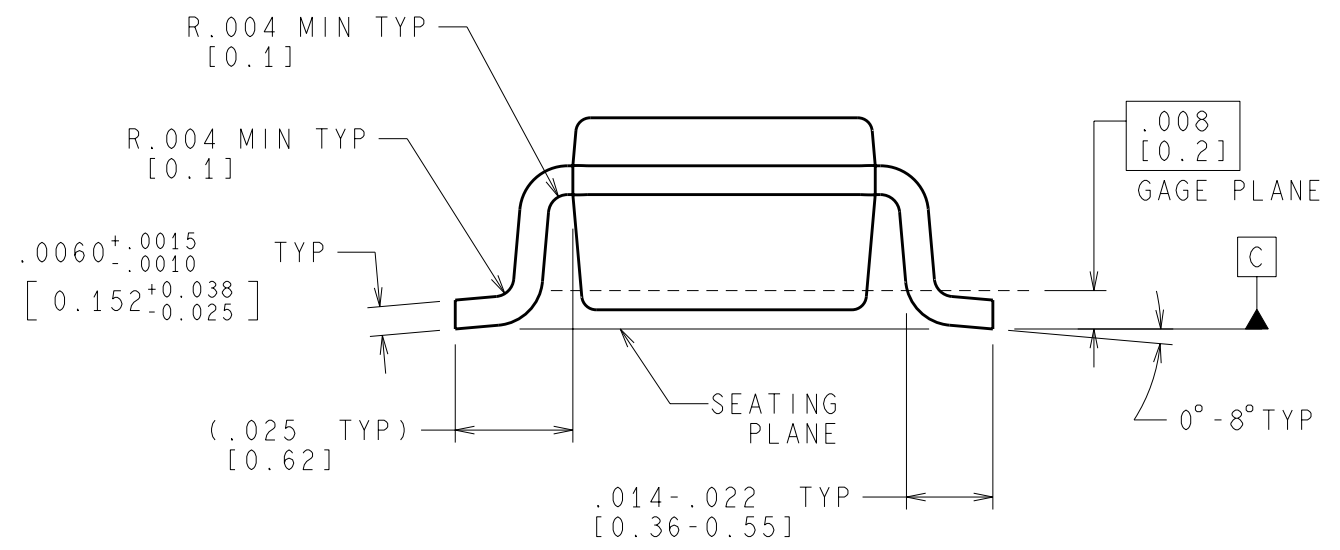
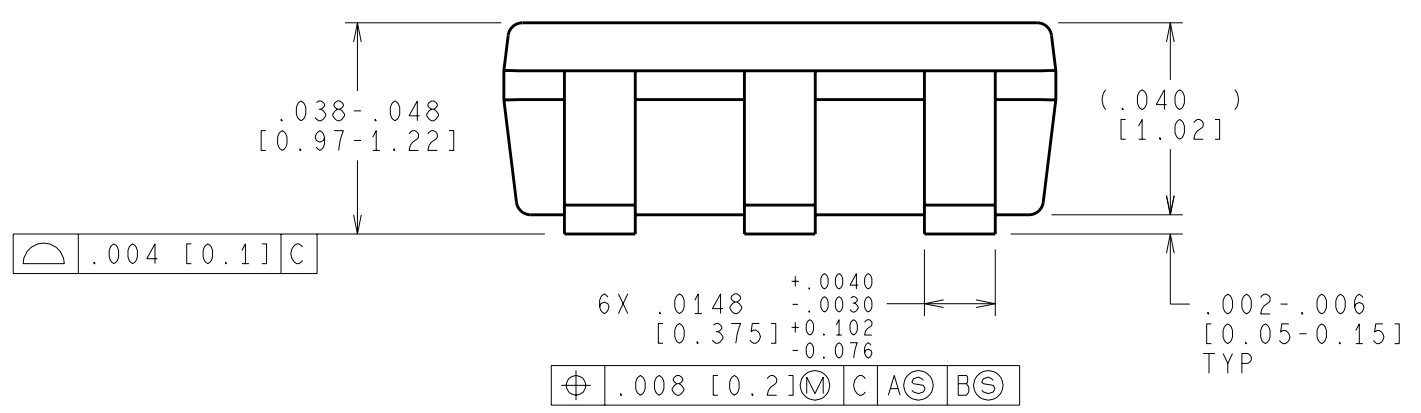


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12345	01/13/2000	TL/RW
B	REVISE NOTE 1; UPDATE NOTE 2; CHANGE DWG FORMAT TO B SIZE	983	04/07/2003	TL/RW
C	LEAD WIDTH WAS .0170+.0025/-0.0020[0.432+0.063/-0.050]	1924	09/30/2005	AS/TL/JL



RECOMMENDED LAND PATTERN



CONTROLLING DIMENSION IS INCH
 VALUES IN [] ARE MILLIMETERS
 DIMENSIONS IN () FOR REFERENCE ONLY

NOTES: UNLESS OTHERWISE SPECIFIED

- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- REFERENCE JEDEC REGISTRATION MO-178, VARIATION AB.

APPROVALS	DATE	National Semiconductor	
DRAWN T. LEQUANG	01/13/2000	2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DTG. CHK. MARTA SUCHY	09/30/2005	MOLDED SOT-23, .115x.063x.040 in, 6 LD, .0375 in PITCH	
ENGR. CHK. ASNOR SULAIMAN	09/30/2005		
PROJECTION		SCALE	SIZE
		NTS	B
INCH (MM)		DRAWING NUMBER	REV
		(SC)MKT-MF06A	C
		FORMERLY: N/A	SHEET 1 of 1